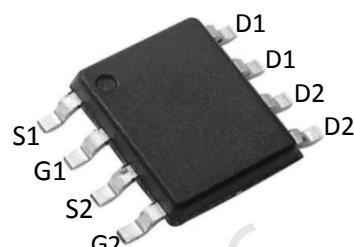


## Description:

This N-Channel and P-Channel MOSFET use advanced trench technology.

Technology To provide excellent RDS(ON), low gate charge.

This device may be used to form a level shifted high side switch, and for a host of other application.

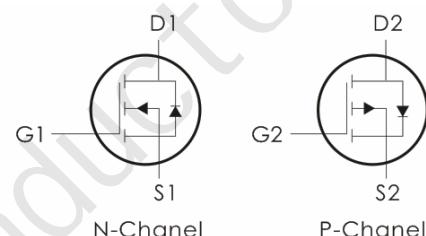


## Features:

N-Channel:  $V_{DS}=100V$ ,  $I_D=2.2A$ ,  $R_{DS(ON)}<152m\Omega$  @  $V_{GS}=10V$

P-Channel:  $V_{DS}=-100V$ ,  $I_D=-1.8A$ ,  $R_{DS(ON)}<200m\Omega$  @  $V_{GS}=-10V$

- 1) Low gate charge.
- 2) Green device available.
- 3) Advanced high cell density trench technology for ultra low  $R_{DS(ON)}$ .
- 4) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Units
$V_{DS}$	Drain-Source Voltage	100	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_A=25^\circ C$	2.2	-1.8	A
	Continuous Drain Current- $T_A=70^\circ C$	1.7	-1.4	
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	13.2	-7.2	A
$P_D$	Power Dissipation	1.5	2	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150		°C

## Thermal Characteristics:

Symbol	Parameter	N-CH	P-CH	Units
$R_{Theta A}$	Thermal Resistance,Junction to Ambient	85	62.5	°C/W
$R_{Theta C}$	Thermal Resistance Junction-Case	25	---	°C/W

N-Channel Electrical Characteristics: ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	100	---	---	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_J=25^\circ\text{C}$	---	---	10	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_J=55^\circ\text{C}$	---	---	100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1.2	---	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	---	---	152	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1\text{A}$	---	---	158	
$G_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=2\text{A}$	---	10.2	---	S
$R_{\text{G}}$	Gate Resistance	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	2.1	---	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1050	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	45	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	30	---	
$Q_{\text{g}}$	Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=80\text{V}$ $I_{\text{D}}=2\text{A}$	---	18.4	---	nc
$Q_{\text{gs}}$	Gate-Source Charge		---	3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	3.1	---	
<b>Switching Characteristics</b>						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}, V_{\text{GS}}=10\text{V},$ $R_{\text{G}}=3.3, I_{\text{D}}=2\text{A}$	---	5.6	---	ns
$t_{\text{r}}$	Rise Time		---	20	---	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		---	28	---	ns
$t_{\text{f}}$	Fall Time		---	24	---	ns

Drain-Source Diode Characteristics						
$V_{SD}$	Source-Drain Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	2.2	ns
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	13.2	nC

N-Channel Typical Characteristics: ( $T_c=25^\circ C$  unless otherwise noted)

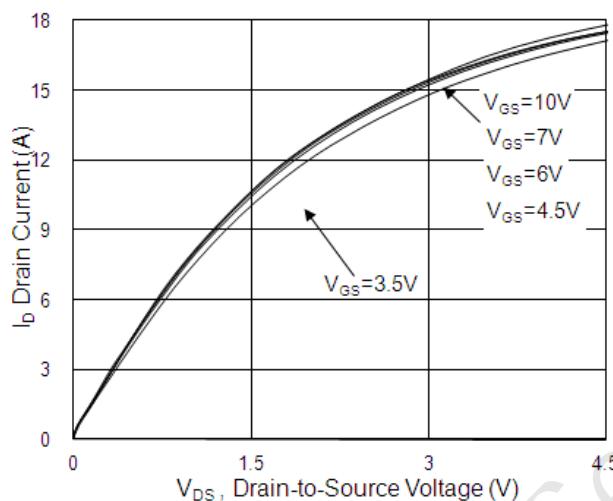


Fig.1 Typical Output Characteristics

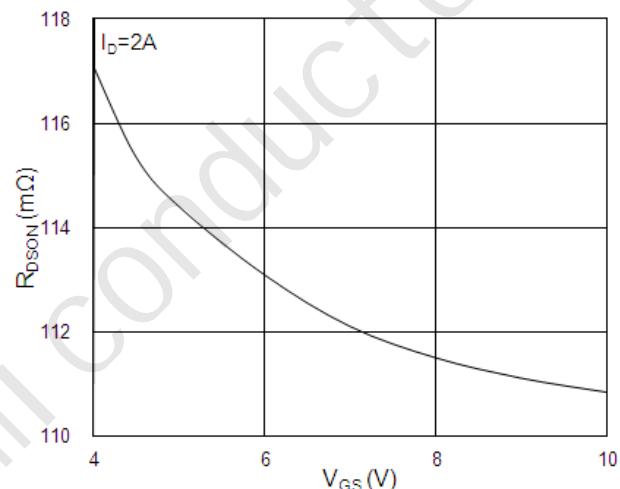


Fig.2 On-Resistance vs. Gate-Source

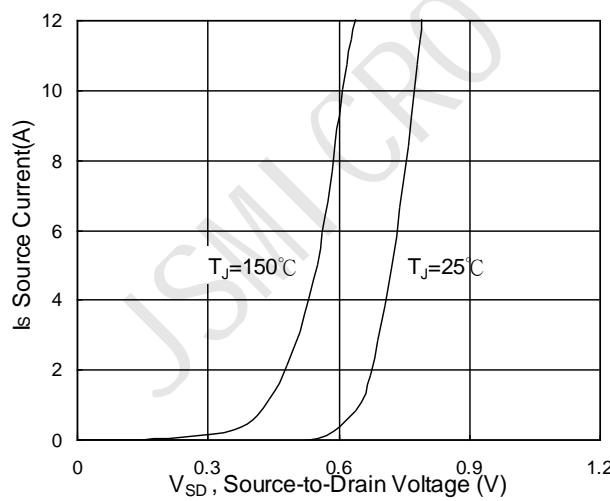


Fig.3 Forward Characteristics Of Reverse

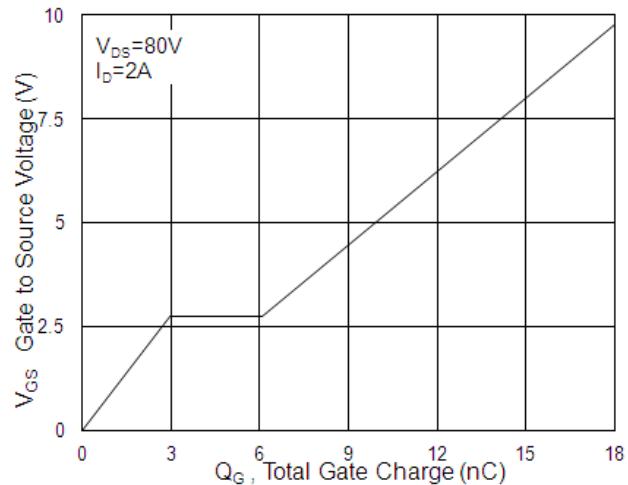
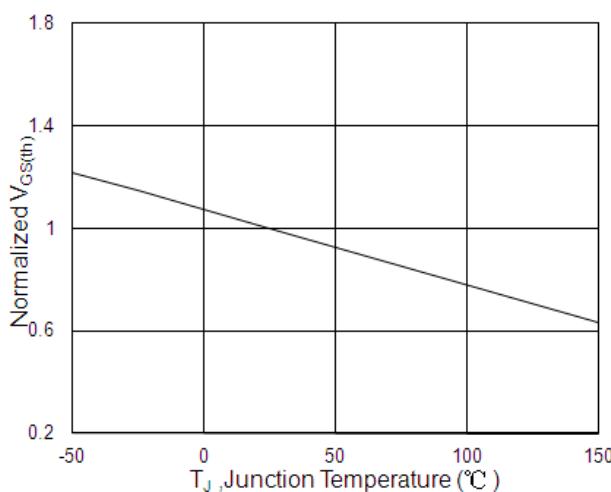
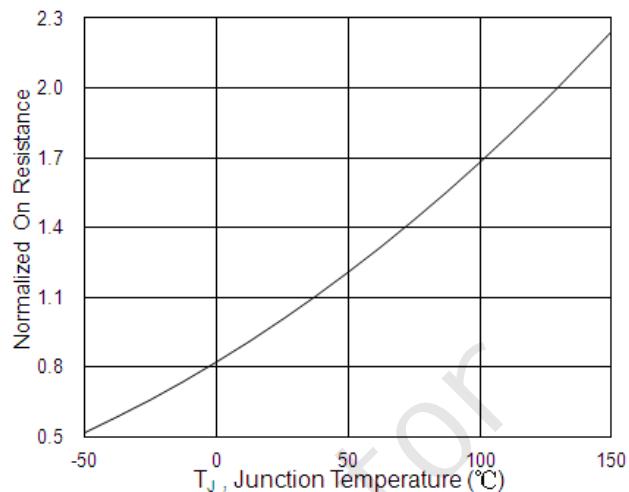
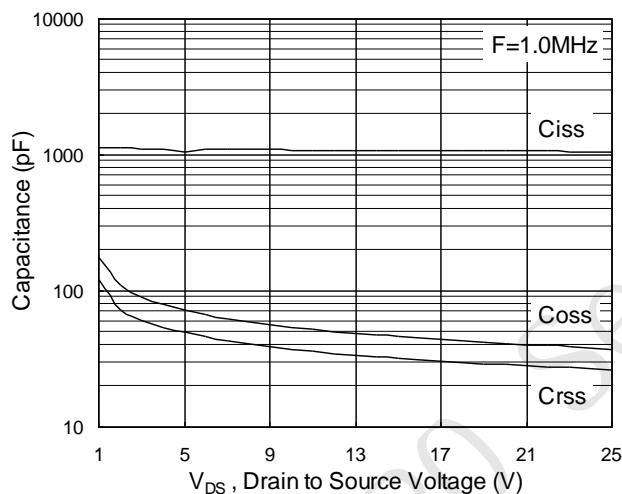
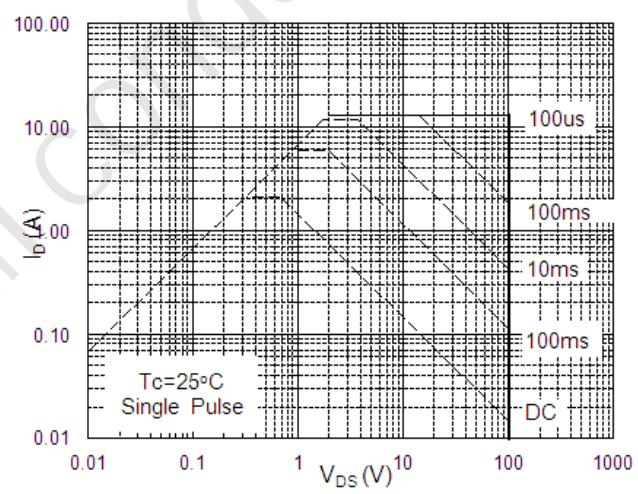
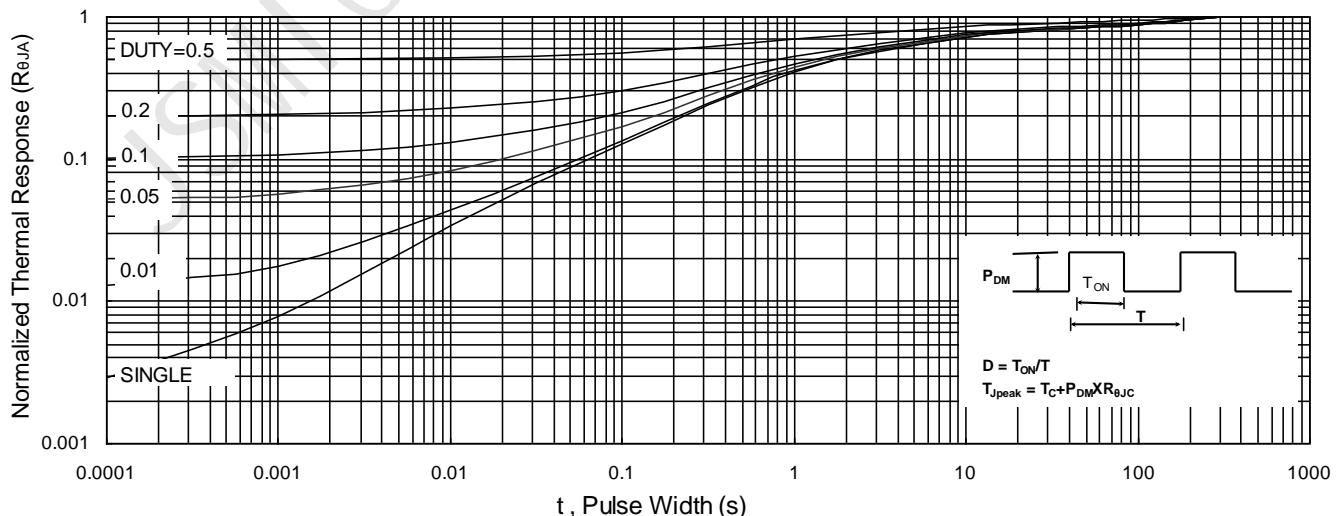
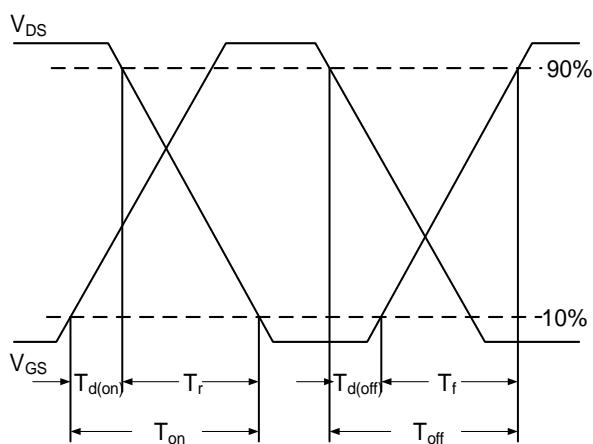
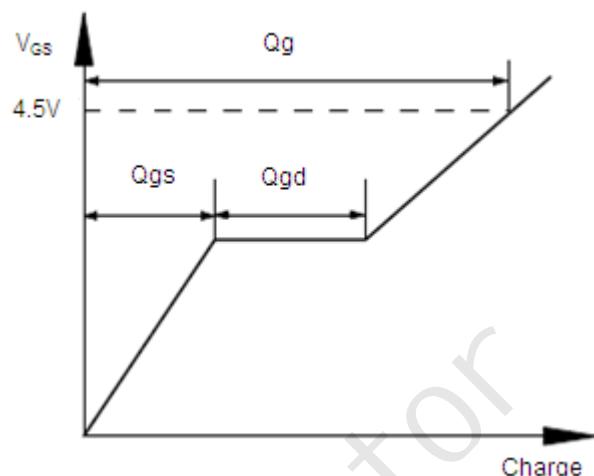


Fig.4 Gate-Charge Characteristics


**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$** 

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**


**Fig.10 Switching Time Waveform**

**Fig.11 Gate Charge Waveform**
**P-Channel Electrical Characteristics:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

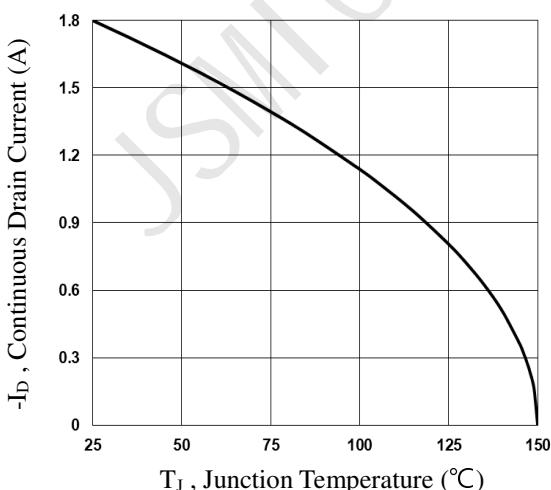
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\mathbf{BV_{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\ \mu\text{A}$	-100	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS}=0\text{V}, V_{DS}=-100\text{V}, T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{GS}=0\text{V}, V_{DS}=-80\text{V}, T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	-1.2	-1.6	-2.5	V
$R_{DS(\text{ON})}$	Drain-Source On Resistance	$V_{GS}=-10\text{V}, I_D=-1.8\text{A}$	---	165	200	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-1.5\text{A}$	---	180	230	
$G_{FS}$	Forward Transconductance	$V_{DS}=-10\text{V}, I_D=-3\text{A}$	---	6.5	---	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-50\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	---	1455	2200	$\text{pF}$
$C_{oss}$	Output Capacitance		---	880	1300	
$C_{rss}$	Reverse Transfer Capacitance		---	58	85	
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	---	16	---	$\Omega$

Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{GS}=-10V, V_{DD}=-50V$ $R_G=25\Omega, I_D=-1.8A$	---	18	36	ns
$t_r$	Rise Time <sup>2,3</sup>		---	8	16	ns
$t_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	100	200	ns
$t_f$	Fall Time <sup>2,3</sup>		---	30	60	ns
$Q_g$	Total Gate Charge <sup>2,3</sup>		---	20	40	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	3.5	7	nC
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	4.6	9	nC
Drain-Source Diode Characteristics						
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1	V
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-1.8	V
$I_{SM}$	Pulsed Source Current		---	---	-3.6	V
$T_{rr}$	Reverse Recovery Time	$V_R=-100V, I_S=-1A$ $dI/dt=100A/\mu s, T_J=25^\circ C$	---	13	---	ns
$Q_{rr}$	Reverse Recovery Charge		---	15	---	nC

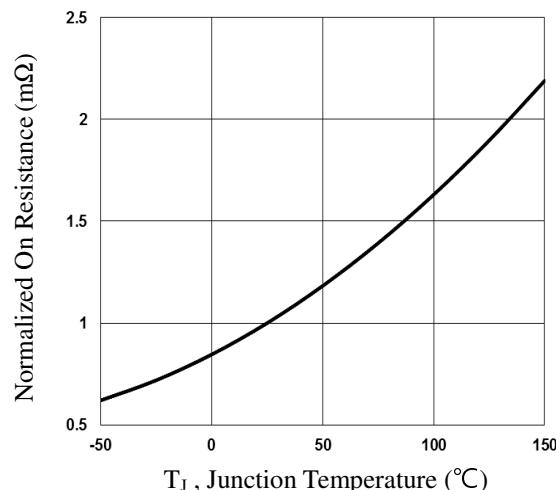
**Notes:**

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

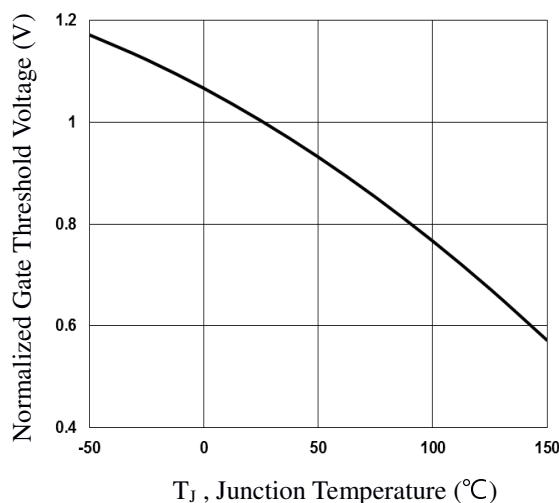
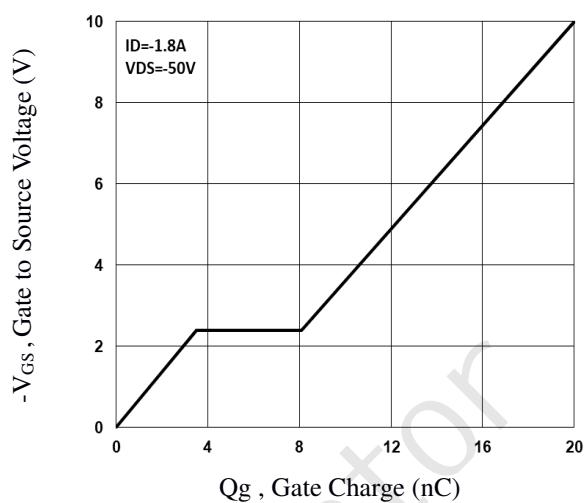
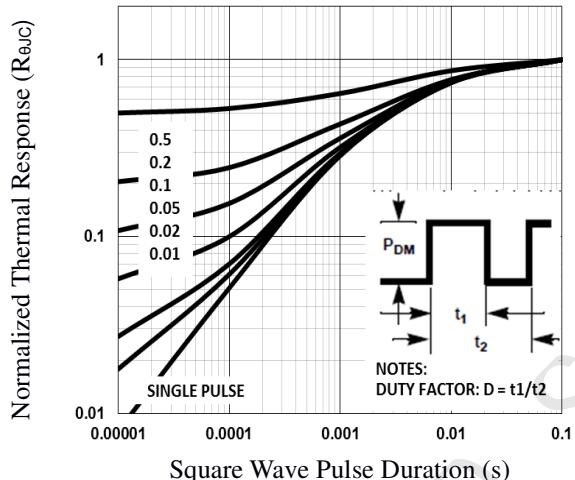
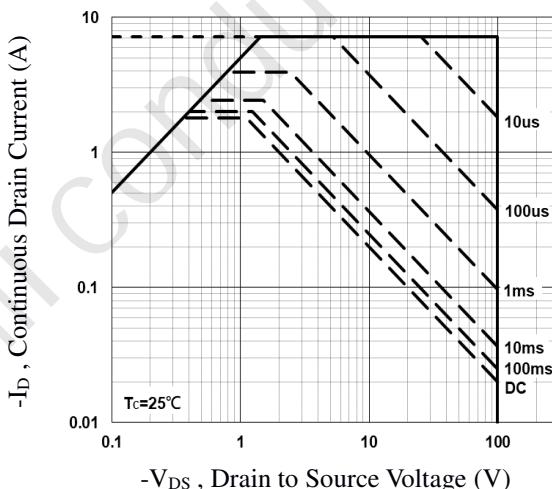
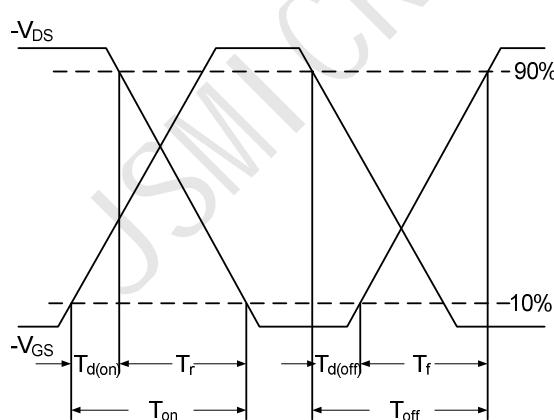
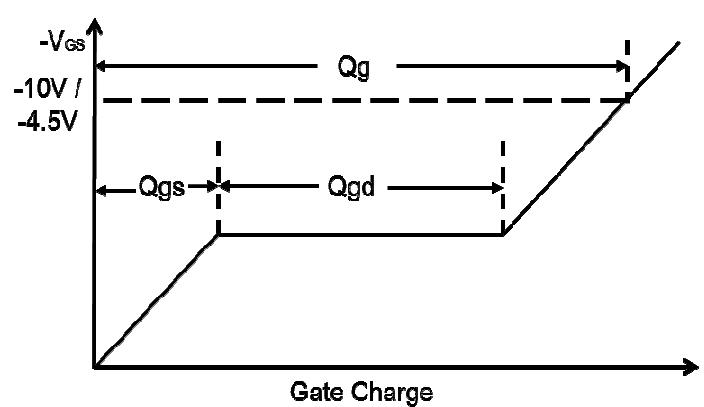
P -Channel Typical Characteristics: ( $T_C=25^\circ C$  unless otherwise noted)

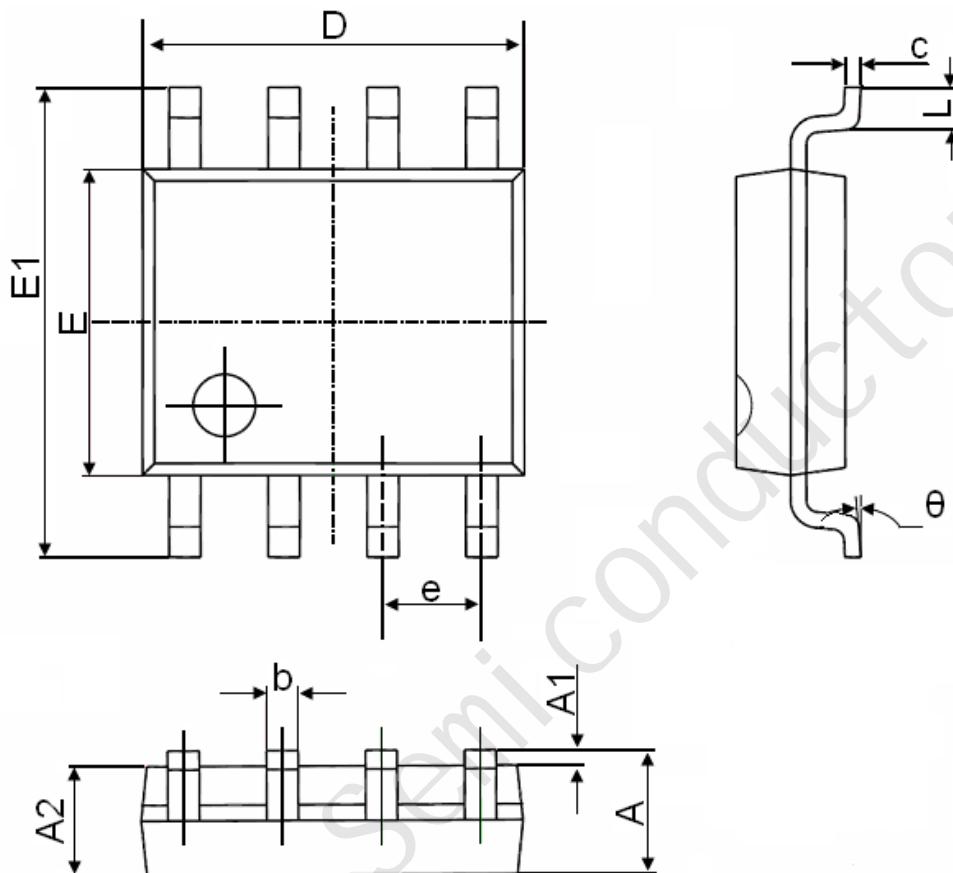


**Fig.1 Continuous Drain Current vs.  $T_J$**



**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**


**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**

**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°